

SSW7N60B / SSI7N60B

600V N-Channel MOSFET

General Description

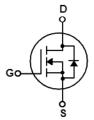
These N-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar, DMOS technology.

This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency switch mode power supplies.

Features

- 7.0A, 600V, $R_{DS(on)} = 1.2\Omega$ @V_{GS} = 10 V
- Low gate charge (typical 38 nC)
- Low Crss (typical 23 pF)
- · Fast switching
- · 100% avalanche tested
- · Improved dv/dt capability





Absolute Maximum Ratings T_C = 25°C unless otherwise noted

Symbol	Parameter		SSW7N60B / SSI7N60B	Units
V _{DSS}	Drain-Source Voltage		600	V
I _D	Drain Current - Continuous (T _C = 25°C)		7.0	А
	- Continuous (T _C = 100°C)		4.4	А
I _{DM}	Drain Current - Pulsed	(Note 1)	28	А
V _{GSS}	Gate-Source Voltage		± 30	V
E _{AS}	Single Pulsed Avalanche Energy	(Note 2)	420	mJ
I _{AR}	Avalanche Current	(Note 1)	7.0	Α
E _{AR}	Repetitive Avalanche Energy	(Note 1)	14.7	mJ
dv/dt	Peak Diode Recovery dv/dt	(Note 3)	5.5	V/ns
PD	Power Dissipation (T _A = 25°C) *		3.13	W
	Power Dissipation (T _C = 25°C)		147	W
	- Derate above 25°C		1.18	W/°C
T _J , T _{stg}	Operating and Storage Temperature Range		-55 to +150	°C
TL	Maximum lead temperature for soldering put 1/8" from case for 5 seconds	rposes,	300	°C

Thermal Characteristics

Symbol	Parameter	Тур	Max	Units
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case		0.85	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient *		40	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient		62.5	°C/W

^{*} When mounted on the minimum pad size recommended (PCB Mount)

Symbol	Parameter	Test Conditions	;	Min	Тур	Max	Units
Off Cha	aracteristics						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} = 0 V, I _D = 250 μA		600			V
ΔBV _{DSS} / ΔT _J	Breakdown Voltage Temperature Coefficient	I _D = 250 μA, Referenced	to 25°C		0.65		V/°C
I _{DSS}		V _{DS} = 600 V, V _{GS} = 0 V				10	μА
	Zero Gate Voltage Drain Current	V _{DS} = 480 V, T _C = 125°C				100	μА
I _{GSSF}	Gate-Body Leakage Current, Forward	V _{GS} = 30 V, V _{DS} = 0 V				100	nA
I _{GSSR}	Gate-Body Leakage Current, Reverse	V _{GS} = -30 V, V _{DS} = 0 V				-100	nA
On Cha	racteristics						
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _D = 250 μA		2.0		4.0	V
R _{DS(on)}	Static Drain-Source On-Resistance	$V_{GS} = 10 \text{ V}, I_D = 3.5 \text{ A}$			1.0	1.2	Ω
g _{FS}	Forward Transconductance	V _{DS} = 40 V, I _D = 3.5 A	(Note 4)		8.2		s
C _{iss} C _{oss} C _{rss}	Input Capacitance Output Capacitance Reverse Transfer Capacitance	$V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V},$ f = 1.0 MHz			1380 115 23	1800 150 30	pF pF
	ing Characteristics						
t _{d(on)}	Turn-On Delay Time	.,			30	70	ns
t _r	Turn-On Rise Time	$V_{DD} = 300 \text{ V}, I_D = 7.0 \text{ A},$			80	170	ns
t _{d(off)}	Turn-Off Delay Time	$R_G = 25 \Omega$			125	260	ns
t _f	Turn-Off Fall Time		(Note 4, 5)		85	180	ns
Qg	Total Gate Charge	V _{DS} = 480 V, I _D = 7.0 A,			38	50	nC
Q _{gs}	Gate-Source Charge	V _{GS} = 10 V			6.4		nC
Q _{gd}	Gate-Drain Charge	- 03	(Note 4, 5)		15		nC
	Source Diode Characteristics at		s			7.0	А
I _{SM}	Maximum Pulsed Drain-Source Diode F	orward Current				28	Α
V _{SD}	Drain-Source Diode Forward Voltage	V _{GS} = 0 V, I _S = 7.0 A				1.4	V
t _{rr}	Reverse Recovery Time	V _{GS} = 0 V, I _S = 7.0 A,			415		ns
Q _{rr}	Reverse Recovery Charge	dl _F / dt = 100 A/μs	(Note 4)		4.6		μС

Notes: 1. Repetitive Rating : Pulse width limited by maximum junction temperature 2. L = 15.7mH, I_{AS} = 7.0A, V_{DD} = 50V, R_S = 25 Ω , Starting T_J = 25°C 3. I_{SD} ≤ 7.0A, di/dt ≤ 300A/µs, V_{DD} ≤ BV_{DSS} Starting T_J = 25°C 4. Pulse Test : Pulse width ≤ 300 μ s, Duty cycle ≤ 2% 5. Essentially independent of operating temperature

Typical Characteristics

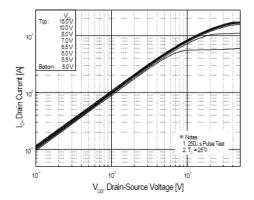


Figure 1. On-Region Characteristics

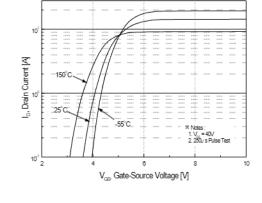


Figure 2. Transfer Characteristics

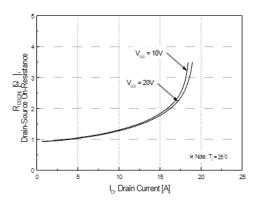


Figure 3. On-Resistance Variation vs Drain Current and Gate Voltage

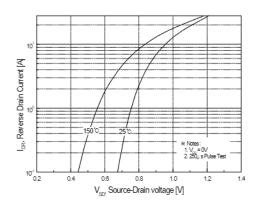


Figure 4. Body Diode Forward Voltage Variation with Source Current and Temperature

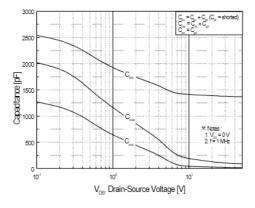


Figure 5. Capacitance Characteristics

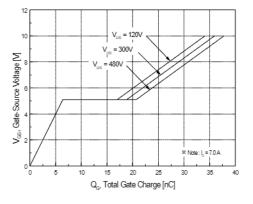


Figure 6. Gate Charge Characteristics

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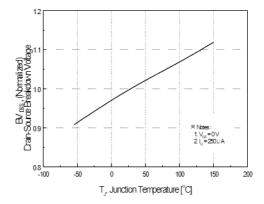


Figure 7. Breakdown Voltage Variation vs Temperature

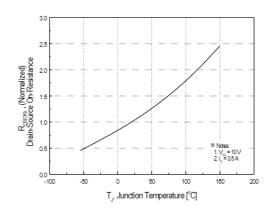


Figure 8. On-Resistance Variation vs Temperature

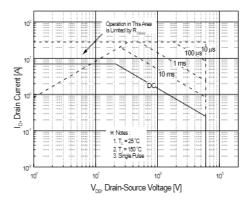


Figure 9. Maximum Safe Operating Area

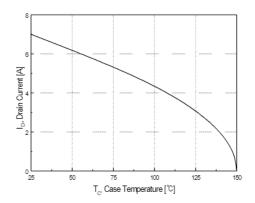


Figure 10. Maximum Drain Current vs Case Temperature

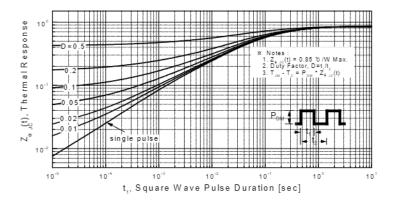
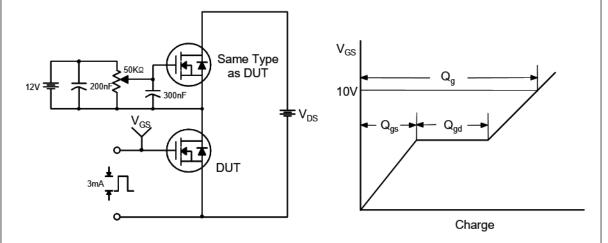


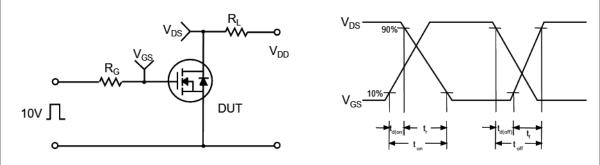
Figure 11. Transient Thermal Response Curve

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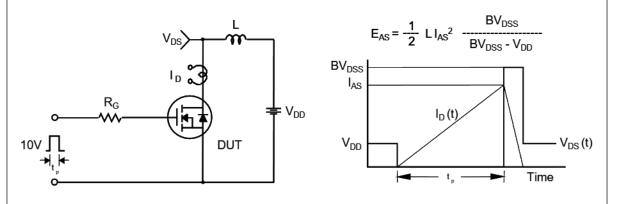
Gate Charge Test Circuit & Waveform



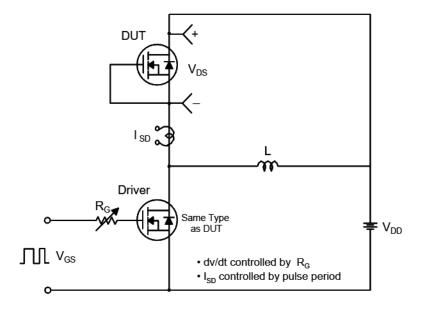
Resistive Switching Test Circuit & Waveforms

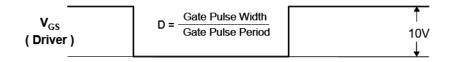


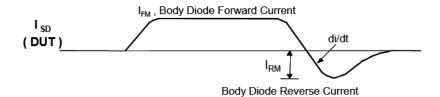
Unclamped Inductive Switching Test Circuit & Waveforms



Peak Diode Recovery dv/dt Test Circuit & Waveforms







Body Diode Recovery dv/dt

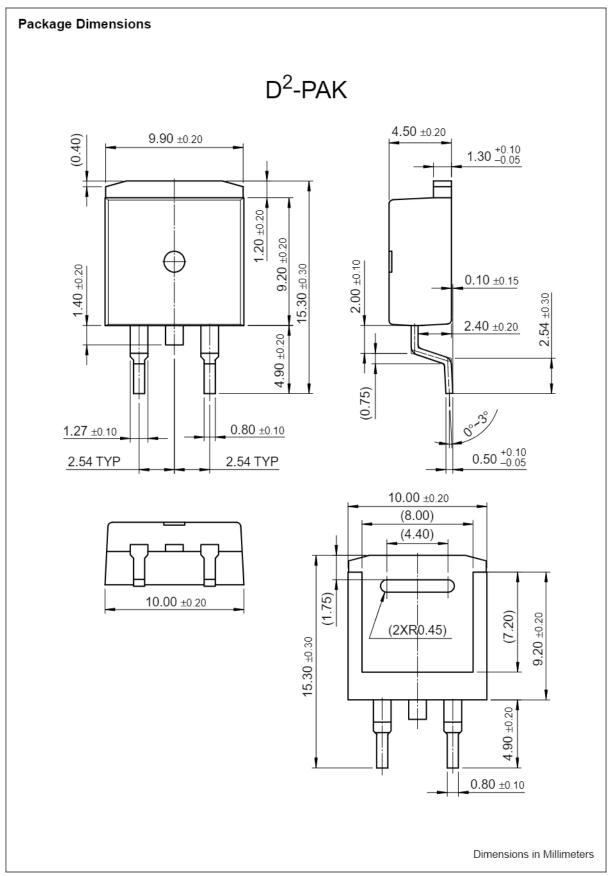
V_{SD}

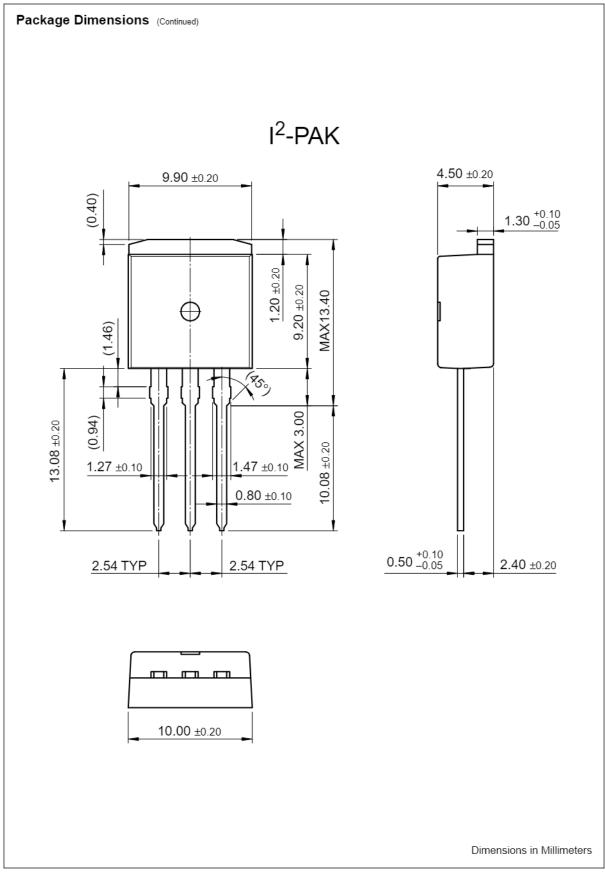
Body Diode

Body Diode

Forward Voltage Drop

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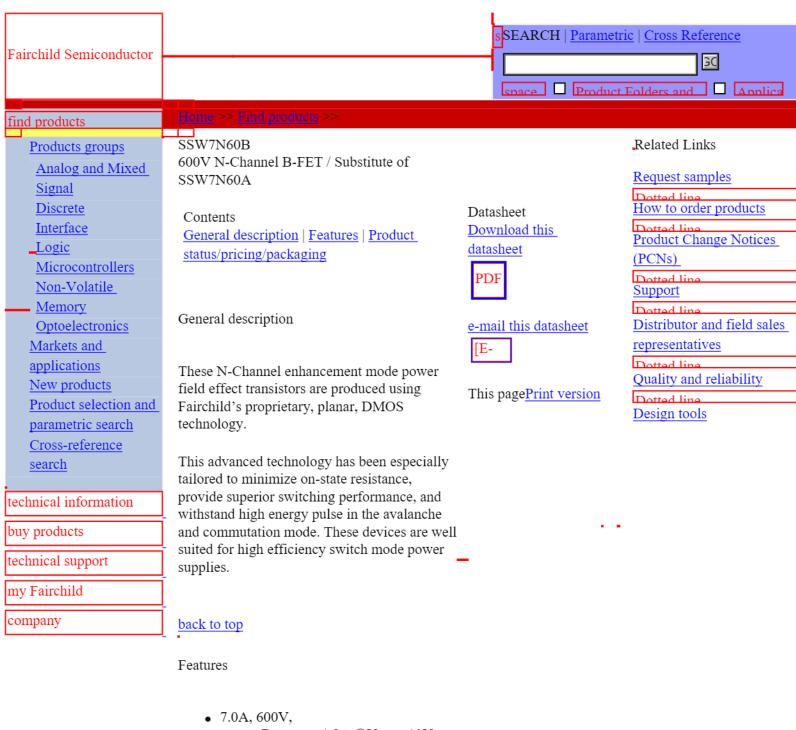
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- $R_{DS(on)} = 1.2\Omega @V_{GS} = 10V$
- Low gate charge (typical 38 nC)
- Low Crss (typical 23 pF)
- Fast switching
- · 100% avalanche tested
- Improved dv/dt capability

Product status/pricing/packaging

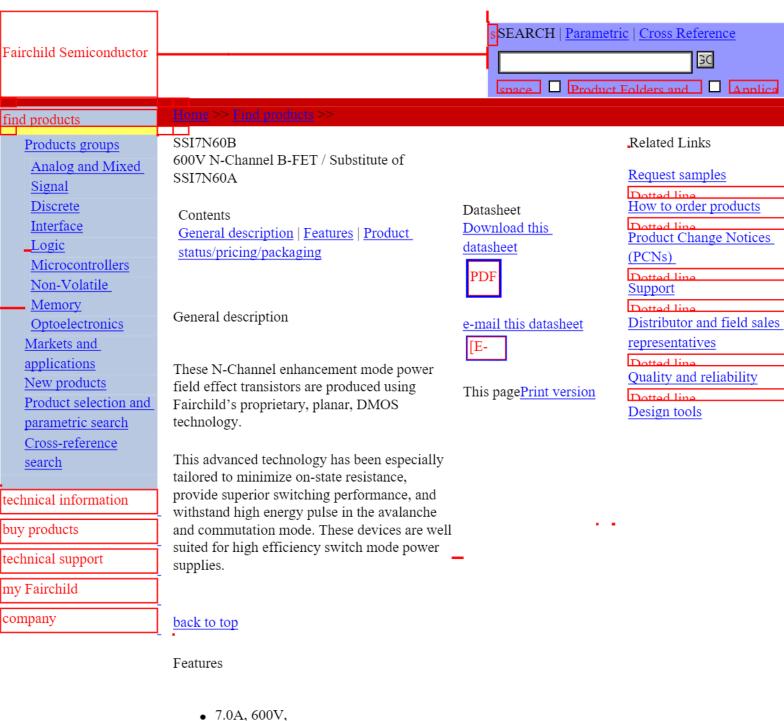
Product	Product status	Pricing*	Package type	Leads	Packing method

SSW7N60BTM	Full Production	\$1.00	TO-263(D2PAK)	2	TAPE REEL

^{* 1,000} piece Budgetary Pricing

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Product status/pricing/packaging

Product	Product status	Pricing*	Package type	Leads	Packing method
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SSI7N60BTU	Full Production	\$1.00	TO-262(I2PAK)	3	RAIL

^{* 1,000} piece Budgetary Pricing

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